

Code No: I0403/R16

M. Tech. I Semester Regular Examinations, December-2016

SPECIAL MANUFACTURING PROCESS

Common to CAD/CAM (04), Advanced Manufacturing Systems (17) and Computer Aided Design & Manufacturing (09)

Time: 3 Hours

Max. Marks: 60

Answer any FIVE Questions
All Questions Carry Equal Marks

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| 1. | a | Describe the principle, advantages, disadvantages and applications of thermal spraying. | 6M |
| | b | Explain the process of chemical vapor deposition in detail. | 6M |
| 2. | a | Explain the applications and characteristics of ceramics in detail. | 6M |
| | b | Write a short notes on Metal Matrix Composites (MMC). | 6M |
| 3. | a | What is surface mount technology? Explain in detail. | 6M |
| | b | What are various film deposition methods used in fabrication of microelectronic devices? | 6M |
| 4. | a | Write a short note on principle, advantages, disadvantages and applications of Wire EDM. | 6M |
| | b | Describe the working principle of laser beam machining. | 6M |
| 5. | | Write short notes on principle, advantages, disadvantages and applications of on Fused Deposition Method. | 12M |
| 6. | | Describe the process of Electro Chemical Machining with a neat sketch. | 12M |
| 7. | | Identify and explain at least two techniques used under rapid manufacturing. | 12M |
| 8. | | Write a short notes on any THREE of the following, | 12M |
| | a | Electro forming | |
| | b | Composite layers | |
| | c | Lithography | |
| | d | Properties of wire used in wire EDM. | |
